

(2,54 mm) .100"

SIGNAL POWER COMBO SYSTEM

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?HPFC or www.samtec.com?HPMC

Insulator Material:

Black Liquid Crystal Polymer

Signal Contact (HPFC):

Phosphor Bronze

Power Contact (HPFC):

BeCu

Terminal (HPMC):

Phosphor Bronze

(Signal & Power)

Plating:

Sn or Au over 50µ" (1,27 µm)

Ni on signal pins; Sn over 50µ" (1,27 µm) Ni on power pins

Operating Temp Range:

-55°C to +105°C with Tin;

-55°C to +125°C with Gold

Contact Resistance:

10 mΩ

Insertion Depth:

(3,68 mm) .145" to

(8,26 mm) .325"

Wiping Distance:

(0,381 mm) .015"

Insertion Force:

(Single contact only)

5 oz (1,39 N) avg. (signal pins)

56 oz (15,57 N) avg. (power pins)

Withdrawal Force:

(Single contact only)

3 oz (0,83 N) avg. (signal pins)

52 oz (14,46 N) avg. (power pins)

Voltage Rating:

850 VAC/1201 VDC

RoHS Compliant:

Yes

Processing:

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0,15 mm) .006" max (02-20)

(0,20 mm) .008" max (21-24)

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



Note:
Some lengths, styles and options are non-standard, non-returnable.

